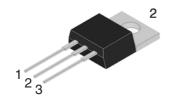
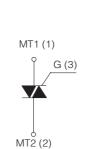


TO-220AB





On-State Current

Gate Trigger Current

8 Amp

≤ 50 mA

Off-State Voltage

400 V ÷ 800 V

FEATURES

- Glass/passivated die junctions
- Medium current Triac
- Low thermal resistance
- High commutation
- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- Component in accordance to RoHS 2011/65/EU and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C

MECHANICAL DATA

- Case: TO-220AB. Epoxy meets UL 94V-0 flammability rating.
- Polarity: As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

TYPICAL APPLICATIONS

• Used on inductive loads, thanks to their high commutation performances.

Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I _{T(RMS)}	RMS On-state Current (full sine wave)	All Conduction Angle, T _c = 95 °C	8	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz (t = 16.7 ms)	84	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz (t = 20 ms)	80	А
I ² t	Fusing Current	tp = 10 ms, Half Cycle	36	A ² s
I _{GM}	Peak Gate Current	20 μs max. Tj = 125 °C	4	А
P _{G(AV)}	Average Gate Power Dissipation	Tj = 125 °C	1	W
dI/dt	Critical rate of rise of on-state current	$I_G = 2x I_{GT}, t_r \le 100 \text{ns}$	50	A/µs
		f = 120 Hz, T _j = 125 °C		
T _j	Operating Temperature		(-40 +125)	°C
T _{stg}	Storage Temperature		(-40 +150)	°C
T _{sld}	Soldering Temperature	10s max	260	°C

SYMBOL	PARAMETER		Unit		
		D	M	N	
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	400	600	800	V

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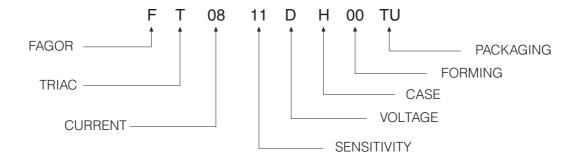


Electrical Characteristics at Tamb = 25 °C

SYMBOL PARAMETER		CONDITIONS		Ouadrant		SENSITIVITY			Heit
STIVIBUL	PARAMETER	CONDITIONS		Quadrant		11	14	16	Unit
I _{GT} ⁽¹⁾	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 339$	Ω , $T_j = 25$ °C	Q1÷Q3	MAX	25	35	50	mA
V _{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 339$	Ω , $T_j = 25$ °C	Q1÷Q3	MAX	X 1.3			V
V_{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \text{ Kg}$	Ω , $T_j = 125 ^{\circ}C$	Q1÷Q3	MIN	0.2		V	
I _H ⁽²⁾	Holding Current	$I_T = 100 \text{ mA,Gate ope}$	en, $T_j = 25$ °C		MAX	25	35	50	mA
IL	Latching Current	$I_{G} = 1.2 I_{GT}, T_{j} = 25 ° C$	0	Q1,Q3	MAX	40	50	70	mA
				Q2	MAX	50	60	80	mA
dV/dt (2)	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$, Ga	te open		MIN	200	400	1000	V/µs
		T _j = 125 °C							
(dl/dt)c (2)	Critical Rate of Current Rise	$(dv/dt)c = 0.1 V/\mu s$	T _j = 125 °C		MIN	-	-	-	A/ms
		$(dv/dt)c = 10 V/\mu s$	$T_j = 125 ^{\circ}\text{C}$		MIN	-	-	-	
		without snubber	$T_j = 125 ^{\circ}\text{C}$		MIN	4.0	4.5	7	
V _{TM} ⁽²⁾	On-state Voltage	$I_T = 11 \text{ Amp, tp} = 380 \mu\text{s,T}_j = 25 ^{\circ}\text{C}$			MAX	IAX 1.55		'	V
V _{t (0)} (2)	Threshold Voltage	T _j = 125 °C			MAX	0.85		V	
r _d ⁽²⁾	Dynamic resistance	T _j = 125 °C			MAX	X 50			mΩ
I _{DRM} /I _{RRM}	Off-State Leakage Current	$V_D = V_{DRM}$, $T_j = 125 ^{\circ}C$			MAX	1		mA	
		$V_R = V_{RRM}$, $T_j = 25 ^{\circ}C$			MAX		5		μΑ
R _{th(j-c)}	Thermal Resistance	for AC 360° conduction angle				1.6		°C/W	
	Junction-Case								
R _{th(j-a)}	Thermal Resistance					60			°C/W
	Junction-Ambient								

⁽¹⁾ Minimum I_{GT} is guaranted at 5% of I_{GT} max.

Part Number Information



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⁽²⁾ For either polarity of electrode MT2 voltage with reference to electrode MT1.

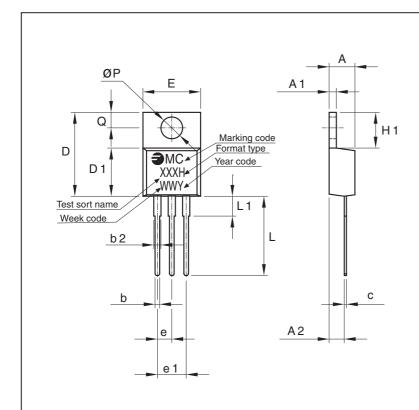




Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FT0816DH 00TU	TU	TUBE	1000	2.30

Package Outline Dimensions: (mm) TO-220AB



	DIMENSIONS			
REF.	Milimeters			
	Min.	Max.		
А	4.47	4.67		
A1	1.17	1.37		
A2	2.52	2.82		
b	0.71	0.91		
b2	1.17	1.37		
С	0.31	0.53		
D	14.65	15.35		
D1	8.50	8.90		
Е	10.01	10.36		
е	2.51	2.57		
e1	4.98	5.18		
H1	6.15	6.45		
L	13.40	13.96		
L1	3.56	3.96		
Р	3.735	3.935		
Q	2.59	2.89		

Mounting Torque 0.8 N.m



Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle)

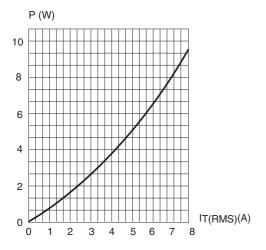


Fig. 3:: Relative variation of thermal impedance versus pulse duration

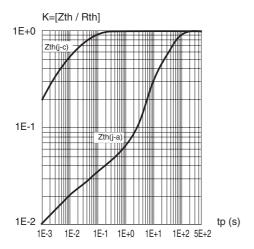


Fig. 5: Surge peak on-state current versus number of cycles

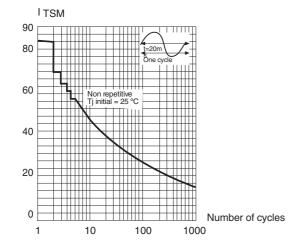


Fig. 2: RMS on-state current versus case temperature (full cycle)

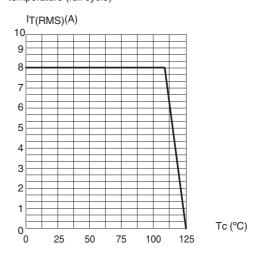


Fig. 4: On-state characteristics (maximum values)

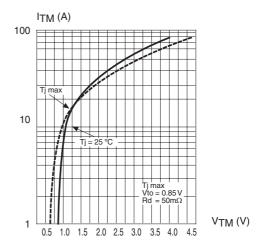
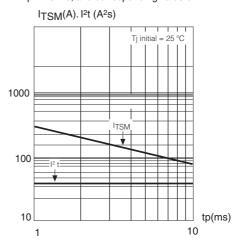


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of l²t.





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

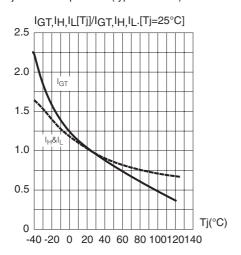
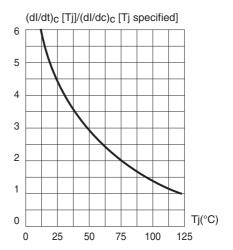


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature





Revision History

Date	Revision	Description of Changes
14-Jun-2011	0	Original Data Sheet
27-Mar-2017 1		200V and 700V eliminated, Change values of: I ² t / V _{TM} / r _d / dV/dt

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